**Material processing**

**Misc**

1. **Solvent Cleaning**  
   Input: Sample/Substrate, Solvent  
   Settings: Temperature (°C), time (minute)  
   Process information:   
   Output:
2. **UV Cleaning**  
   Input: Sample/Substrate,   
   Settings: pressure (mbar), time (minute)  
   Process information:   
   Output:
3. **Plasma Cleaning**  
   Input: Sample/Substrate,   
   Settings: pressure (mbar), power(W), type [‘oxygen’, ‘nitrogen’], time (minute)  
   Process information:   
   Output:
4. **Annealing**  
   Input: Sample/Substrate,   
   Settings: Temperatue (°C), time (s), humidity (nd)  
   Process information:   
   Output:
5. **Storing**  
   Input: Sample/Substrate,   
   Settings: start date, end date, duration (s), start humididy (nd), end humidity (nd)  
   Process information:   
   Output:
6. **Solution Manufacturing**  
   Input: Sample/Substrate, Solvents, Solutes/Powder, Solution  
   Settings: powder mass (mg), solvent/solution volume (ml), concentration, ratio  
   Process information: type [shaker, waiting, ultra sonic], duration (minute), speed (rpm), temperature (°C)  
   Output: Solution
7. **Gas Quenching:**

Input: Sample/Substrate,   
Settings:   
Process information:   
Output:

1. **Solvent Quenching:**

Input: Sample/Substrate,   
Settings:   
Process information:   
Output: